

L3803L-VB Datasheet

N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (Typ)			
30	0.0023 at V _{GS} = 10 V	150	82 nC			
	0.0032 at V _{GS} = 4.5 V	120	02 110			
	TO-262		D Q			

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Top View

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N-Channel MOSFET

FEATURES

- Trench Power MOSFET
- 100 % R_g and UIS Tested
 Compliant to RoHS Directive 2011/65/EU

APPLICATIONS

- OR-ing
- Server
- DC/DC

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V _{GS}		± 20	
	T _C = 25 °C		150	A	
Continuous Drain Current (T = $175 ^{\circ}\text{C}$)	T _C = 70 °C		120		
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	35.8 ^{b, c}		
	T _A = 70 °C		27 ^{b, c}		
Pulsed Drain Current	I _{DM}	500			
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	39		
Single Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	94.8	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	1	90 ^{a, e}		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	3.13 ^{b, c}	— A	
	T _C = 25 °C		250 ^a	w	
Maximum Davier Dissis ation	T _C = 70 °C	PD	175		
Maximum Power Dissipation	T _A = 25 °C	۲D	3.75 ^{b, c}		
	T _A = 70 °C		2.63 ^{b, c}		
Operating Junction and Storage Temperature Ra	T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^{b, d}	$t \le 10 \text{ sec}$	R _{thJA}	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.5	0.6	C/W	

Notes:

a. Based on $T_C = 25 \text{ °C}$. b. Surface mounted on 1" x 1" FR4 board.

c. t = 10 sec. d. Maximum under steady state conditions is 90 °C/W.

COMPLIANT

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 250 \mu A$	30			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L _ 250 uA		35			
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 7.5		mV/°(
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1.5		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
	oltage Drain Current I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1		
Zero Gate Voltage Drain Current		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			μA 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			А	
		V _{GS} = 10 V, I _D = 38.8 A	0.0023				
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 37 A		0.0032		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 38.8 A		160		S	
Dynamic ^b						1	
Input Capacitance	C _{iss}			6201		pF	
Output Capacitance	C _{oss}	V _{DS} = 15 V, V _{GS} = 0 V, f = 1 MHz		1725			
Reverse Transfer Capacitance	C _{rss}			970			
		V _{DS} = 15 V, V _{GS} = 10 V, I _D = 38.8 A		171	257	257 123 nC	
Total Gate Charge	Qg			81.5	123		
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 28.8 \text{ A}$		34			
Gate-Drain Charge	Q _{gd}			29			
Gate Resistance	R _g	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t _{d(on)}			18	27		
Rise Time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_{\text{I}} = 0.625 \Omega$		11	17	1	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 24$ A, V_{GEN} = 10 V, R_g = 1 Ω		70	105	1	
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			55	83	ns	
Rise Time	t _r	$V_{DD} = 15 \text{ V}, \text{ R}_{1} = 0.67 \Omega$		180	270	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 22.5 \text{ A}, \text{ V}_{\text{GEN}} = 4.5 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		55	83		
Fall Time	t _f	-		12	18	1	
Drain-Source Body Diode Characteristic	cs					1	
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			120	Ι.	
Pulse Diode Forward Current ^a	I _{SM}				120	A	
Body Diode Voltage	V _{SD}	I _S = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			52	78	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			70.2	105	nC	
Reverse Recovery Fall Time	t _a	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		27		<u> </u>	
Reverse Recovery Rise Time t _b			-	25		ns	

Notes:

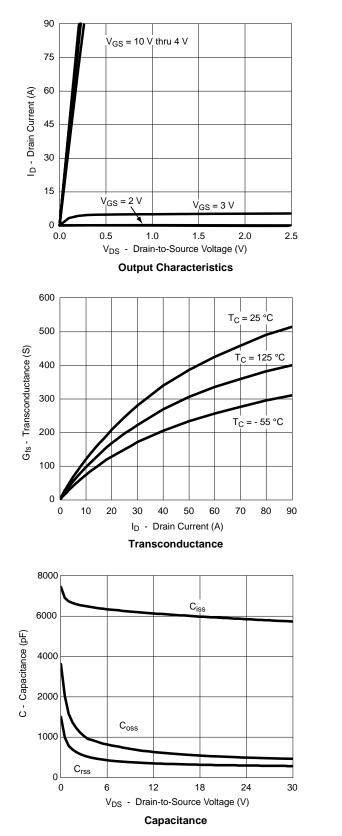
a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle ≤ 2 %.

b. Guaranteed by design, not subject to production testing.

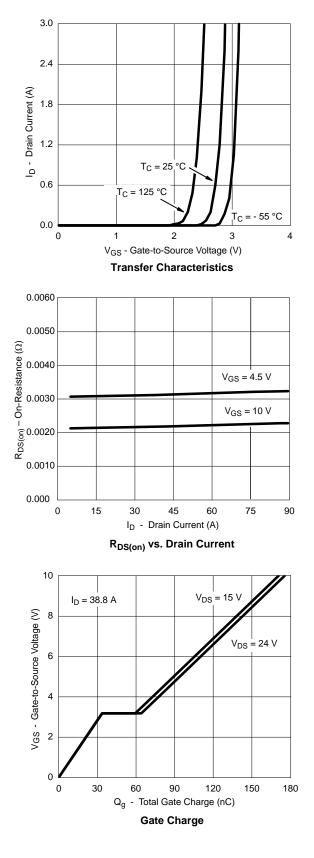
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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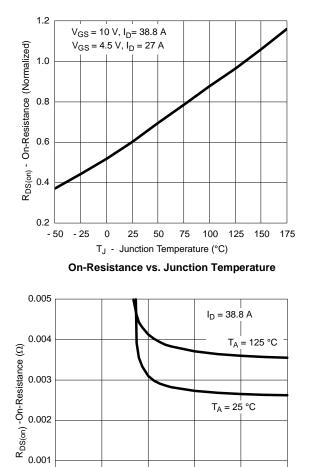




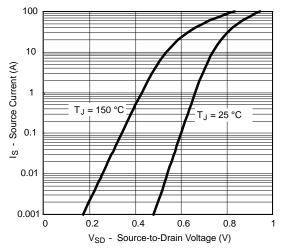
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



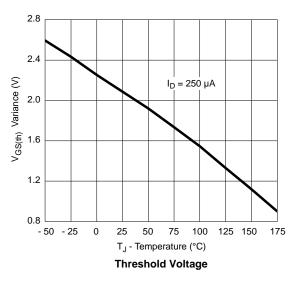


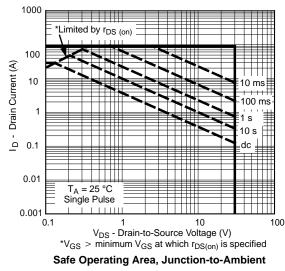


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)









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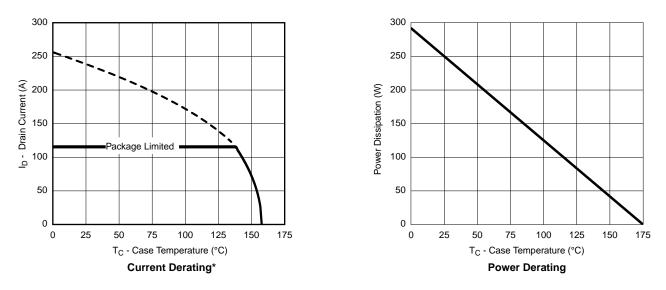
 V_{GS} - Gate-to-Source Voltage (V)

R_{DS(on)} vs. V_{GS} vs. Temperature

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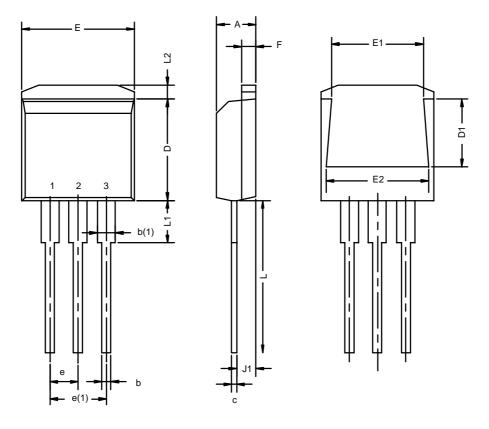
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

*The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





TO-262: 3-LEAD



	MILLIM	ETERS*	INCHES		
Dim	Min	Max	Min	Max	
Α	4.32	4.70	0.170	0.185	
b	0.64	1.00	0.025	0.039	
b(1)	1.14	1.40	0.045	0.055	
С	0.36	0.50	0.014	0.020	
D	8.64	9.65	0.340	0.380	
D1	5.59	6.10	0.220	0.240	
е	2.41	2.67	0.095	0.105	
e(1)	4.95	5.33	0.195	0.210	
E	10.03	10.41	0.395	0.410	
E1	7.87	8.64	0.310	0.340	
E2	9.02	9.53	0.355	0.375	
F	1.14	1.40	0.045	0.055	
J1	2.41	2.79	0.095	0.110	
L	13.08	14.22	0.515	0.560	
L1	-	3.81	-	0.150	
L2	1.02	1.40	0.040	0.055	
ECN: T-02234—Rev. C, 14-Oct-02 DWG: 5855					

*Use millimeters as the primary measurement



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